L Number	Hits		DB	Time stamp
-	1	(knife adj ring) near (movable or moveable	USPAT;	2004/09/22 10:02
		or positionable)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	204	knife adj ring	IBM_TDB	0004400400
		, mile adj ling	USPAT; US-PGPUB;	2004/09/20 11:59
			EPO; JPO;	
			DERWENT;	
			IBM TDB	İ
_	0	(("15156.DID.").PN.) and (wafer or	USPAT;	2004/09/20 12:00
		semiconductor)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	1
_	9	(knife adi mina) and (m.f.	IBM_TDB	
_		(knife adj ring) and (wafer or semiconductor)	USPAT;	2004/09/20 12:03
		Seniconductory	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	233	134/149.ccls.	USPAT;	2004/09/20 12:03
		· ·	US-PGPUB;	2301,03,20 12.03
			EPO; JPO;	
			DERWENT;	
		124/140	IBM_TDB	
_	46	134/149.ccls. and (wafer or semiconductor)	USPAT;	2004/09/20 12:16
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	650	134/184.ccls.	USPAT;	2004/09/20 12:16
			US-PGPUB;	2004/03/20 12:10
ļ			EPO; JPO;	
			DERWENT;	
	^1^	124/104	IBM_TDB	
-	212	134/184.ccls. and (wafer or semiconductor)	USPAT;	2004/09/20 12:24
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	717	134/186.ccls.	USPAT;	2004/09/20 12:24
			US-PGPUB;	-301,03,20 12.24
			EPO; JPO;	
			DERWENT;	
	101	124/106 1-	IBM_TDB	
-	151	134/186.ccls. and (wafer or semiconductor)	USPAT;	2004/09/20 12:24
			US-PGPUB;	
1			EPO; JPO; DERWENT;	[
ľ			IBM TDB	
	9		USPAT;	2004/09/20 12:25
		semiconductor)) and knife	US-PGPUB;	
ľ			EPO; JPO;	
ĺ			DERWENT;	·
_	- 5	(air adi knifa)	IBM_TDB	0004/05/55
	. 5	(air adj knife) near (movable or moveable or positionable)	USPAT;	2004/09/22 10:03
	l	or besteroughte)	US-PGPUB; EPO; JPO;	
			DERWENT;	
ļ		1	IBM TDB	
-	134	(air adj knife) same (movable or moveable	USPAT;	2004/09/22 10:11
-		or positionable)	US-PGPUB;	
		İ	EPO; JPO;	
			DERWENT;	
	1540045		IBM_TDB	,
-	1540045	wafer or semiconductor	USPAT;	2004/09/22 10:12
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
L			IBM TDB	

-	20	( () (	USPAT;	2004/09/22 10:14
		or positionable)) and (wafer or	US-PGPUB;	
	i	semiconductor)	EPO; JPO;	
		·	DERWENT;	
			IBM TDB	
-	296	134/148.ccls.	USPĀT;	2004/09/22 10:14
			US-PGPUB;	2004/03/22 10.14
			EPO; JPO;	
	1	·		
-			DERWENT;	
		124/140 1	IBM_TDB	
-	65	134/148.ccls. and (wafer or semiconductor)	USPAT;	2004/09/22 10:30
			US-PGPUB;	
			EPO; JPO;	
		,	DERWENT;	
			IBM TDB	
-	797	134/153.ccls.	USPAT;	2004/09/22 10:30
			US-PGPUB;	2001,03,22 20.00
			EPO; JPO;	1
			DERWENT;	
-			IBM TDB	
_	6	(134/153.ccls. and (wafer or		2004/00/00 10 01
	1	demigranductor) and (sin some (the shell)	USPAT;	2004/09/22 10:31
		semiconductor)) and (air same ((backside	US-PGPUB;	
		or underside) near wafer))	EPO; JPO;	
		Í	DERWENT;	[
			IBM_TDB	
-	291	134/153.ccls. and (wafer or semiconductor)	USPAT;	2004/09/22 10:43
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	:
_	171	134/154.ccls.	USPAT;	2004/09/22 11:38
	1,1	131/131.0013.		2004/09/22 11:38
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2190	134/902.ccls.	USPAT;	2004/09/22 11:38
			US-PGPUB;	
			EPO; JPO;	
			DERWENT:	
			IBM TDB	
_	37	134/902.ccls. and (air adj knife)	USPAT;	2004/09/22 11:48
	-	,, and (all day mill)	US-PGPUB;	2004/03/22 11.40
				ŀ
1	1		EPO; JPO;	
	[	•	DERWENT;	]
_		lain add //accola au day a lais a	IBM_TDB	
-		air adj ((nozzle or jet or knife) same	USPAT;	2004/09/22 11:49
	J	(wafer near backside))	US-PGPUB;	
		· ·	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	11	air same ((nozzle or jet or knife) same	USPĀT;	2004/09/22 11:53
		(wafer near backside))	US-PGPUB;	
		· *	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	9711	"taiwan semiconductor".as.		2004/00/22 11 5:
	] //11	carwan semiconductor .ds.	USPAT;	2004/09/22 11:54
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	
-	3	THE STATE OF THE S	USPĀT;	2004/09/22 11:55
		ring)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
	1540045	wafer or semiconductor	USPAT;	2004/08/20 12:04
			·	2004/09/20 12:04
			US-PGPUB;	1
			EPO; JPO;	
			DERWENT;	İ
			IBM TDB	

_	1540045	wafer or semiconductor	HCDAM.	10001/00/00
	10.00.0	water or semiconductor	USPAT;	2004/09/22 13:23
			US-PGPUB;	İ
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	236056	(knife adj edge) or (knife adj ring) or divider	USPAT;	2004/09/22 13:24
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	11653	((knife adj edge) or (knife adj ring) or	USPAT;	2004/09/22 13:25
		divider) same (backside or rear or (back	US-PGPUB;	2004/03/22 13.23
		adj side) or reverse)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1755225	((knife adj edge) or (knife adj ring) or	USPAT;	2004/00/00 22 06
		divider) same (backside or rear or (back		2004/09/22 13:26
		adj side) or reverse) near[25] (adjustable	US-PGPUB;	i
		or movable or moveable or positionable)	EPO; JPO;	i
		or movable of moveable of positionable)	DERWENT;	
_	1265	lination on combining the state of	IBM_TDB	
	1203	that of being conductor, and ((killing ad)	USPAT;	2004/09/22 13:27
		edge) or (knife adj ring) or divider) same	US-PGPUB;	
		(backside or rear or (back adj side) or	EPO; JPO;	
		reverse))	DERWENT;	
	_		IBM_TDB	
-	5	((wafer or semiconductor) and (((knife adj	USPAT;	2004/09/22 13:27
·		edge) or (knife adj ring) or divider) same	US-PGPUB;	
		(backside or rear or (back adj side) or	EPO; JPO;	
		reverse))) and 134/\$.ccls.	DERWENT;	
			IBM TDB	

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